

CLAIMS

1. A resin substrate having a resin-metal composite layer that metallic particles are dispersed in a resin matrix at a surface of the resin substrate.
2. The resin substrate having a resin-metal composite layer set forth in claim 1, wherein said resin-metal composite layer is from 20 to 2000 nm in thickness.
3. The resin substrate having a resin-metal composite layer set forth in claim 1, wherein said resin-metal composite layer is a transparent conductive layer which is 200 nm or less than 200 nm in thickness.
4. A method for manufacturing a resin substrate having a resin-metal composite layer at a surface thereof, comprising:  
a pretreatment process that a surface of the resin substrate is modified to a modified layer having a polar group, and  
an adsorbing process that at least either metal colloids or ions are adsorbed to the polar group by contacting the modified layer with a metal compound solution, whereby metal particles are dispersed into the modified layer.
5. A method for manufacturing a resin substrate having a resin-metal composite layer at a surface thereof set forth in claim 4, wherein after said adsorbing process, a metal coating is formed on the surface of said modified layer by electroless plating, thereafter remove said metal coating.